

PULSED LASER DIODE L6690-53

FEATURES

Peak Output Power : ≥10 W

Peak Emission Wavelength: 870 nm
 Emission Area Size: 100 μm × 1 μm

APPLICATIONS

- Laser Range Finder (Entertainment, Measuring Instrument)
- Security (Traffic, Anti-collisium)
- Surveyllance (Robot, Alignment)



■OUTLINES

Pulsed Laser Diode L6690-53 is a high efficiency multimode laser of peak power more than 10 W from $100\,\mu\,\text{m} \times 1\,\mu\,\text{m}$ emitting area. It can be applied for various applications such as Laser Range Finders, Security, Surveyllance etc.

■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit	
Pulsed Foward Current	I fp	15	А	
Reverse Voltage	Vr	2	V	
Pulse Duration (FWHM)	tw	100	ns	
Duty Ratio	DR	0.075	%	
Operating Temperature	Top(c)	-40 to +85	°C	
Storage Temperature	Tstg	-40 to +100	°C	

■ELECTRICAL AND OPTICAL CHARACTERISTICS (Top(c)=25 °C)

Parameter	Symbol	Condition	Value			Unit
			Min.	Тур.	Max.	Unit
Pulsed Radiant Power (Peak Power)	Фер		9	11	-	W
Forward Voltage	V _f	1 1	-	4	-	V
Peak Emission Wavelength	λр	Ifp = 10 A	860	870	880	nm
Spectral Radiation Half Bandwidth	Δλ		-	4	-	nm
Rise Time	tr		-	-	2	ns
Beam Spread Angle : Parallel	θ//	Ifp = 10 A	7	10	13	degree
: Vertical	θ⊥	FWHM	25	30	35	degree
Lasing Threshold Current	Ith	-	-	0.5	-	А
Emission Area	-	Value at designing	-	100 × 1	-	μm

Note: General operating condition: Pulse Width $t_W = 50$ ns, Repetition frequency $f_r = 1$ kHz

PULSED LASER DIODE L6690-53

Figure 1: Radiant Power vs. Pulsed Forward Current (Typ.)

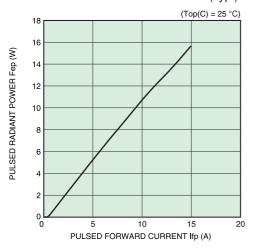
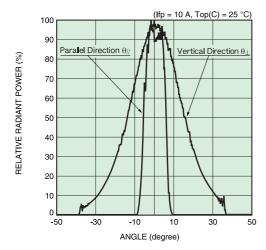


Figure 3: Directivity (Typ.)



Handling Precautions for L6690-53

1. Precautions for handling

The LD (laser diode) may be damaged or its performance may deteriorate due to such factors as electrostatic discharge from the human body, surge voltages from measurement equipment, leakage voltages from soldering irons, and packing materials. As a countermeasure against static electricity, the device, operator, work place and measuring jigs must all be set at the same electric potential. In using LD, observe the following precautions:

•To protect the device from static electricity charges which accumulate on the operator or the operator's clothes, use a wrist strap etc. to ground the operator's body via a high impedance resistor (1 $M\Omega$).

•A semiconductive sheet should be laid on both the work table and the floor in the work area. When soldering, use an electrically grounded soldering iron with an isolation resistance of more than 10 $M\Omega$.

•For containers for transportation and packing, use of antistatic material (material that minimizes the generation of static change when rubbed against or separated from itself or other similar materials).

2. Precautions for mounting

(1)Lead forming

To form the leads, hold the base of the leads securely and bend them so that no force is applied to the package. Lead forming should be done before soldering.

(2)Cutting off the leads

If leads are out when still at a high temperature, this may cause an electrical discontinuity. Always cut off the leads when they are at room temperature. Never cut off the leads immediately after they are soldered.

Figure 2: Emission Spectrum (Typ.)

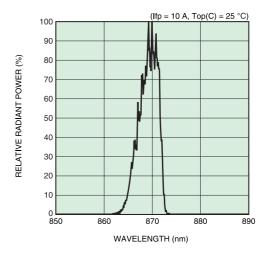
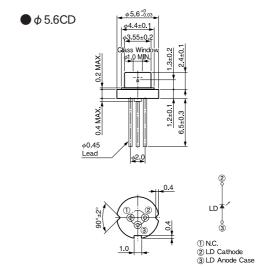


Figure 4: Dimensional Outline (unit: mm)



(3)Soldering

Using a low-temperature melting solder (below 200 °C), solder the leads at the temperature and dwell time specified as follows.

Maximum Soldering Temperature: 230 °C

Maximum Soldering Time: 5 seconds (1 second for devices having a lead length less than 2 mm)

If these conditions cannot be met, it is recommended that some form of heat sink be used at the base of the lead so that the solder heat is not conducted to the package. Also be careful not to apply excessive force to

the leads during soldering.

Soldering at excessive temperatures and dwell times may cause the roots of the leads to crack, resulting in performance deterioration. This sometimes leads to wiring breakage. If the leads are soldered while external force is applied to the device, the residual force tends to degrade device performance. Care should also be taken not to apply force to the

leads during soldering.

In addition, when soldering an LD use a soldering iron with its metallic parts grounded to prevent damage to the device from static discharge. Do not use any flux which is highly acidic. alkaline or inorganic because it may cause the component leads to erode. Use a rosin flux.

3.Protection against laser beams
The LD is classified into class 3B according to the laser product standards of the IEC825-1 (Radiation safety of laser products Part1: Equipment classification, requirements and user's guide). The operator must avoid eye or skin exposure to the laser beam. When viewing the laser beam, be sure to wear safety goggles that block infrared radiation.

HAMAMATSU PHOTONICS K.K.

HAMAMATSU PHOTONICS K.K., Laser Group, Laser Business Promotion Group

1-8-3, Shinmiyakoda, Kita-ku, Hamamatsu City, Shizuoka, 431-2103, Japan, Telephone: (81)53-484-1301, Fax: (81)53-484-1302, E-mail: laser-g@lsr.hpk.co.jp

U.S.A.: Hamamatsu Corporation:360 Foothill Road, Bridgewater, N.J. 08807-0910, U.S.A.Telephone: (1)908-231-0960, Fax: (1)908-231-1218 E-mail: usa@hamamatsu.com
Germany: Hamamatsu Photonics Deutschland GmbH: Arzbergerstr. 10, D-82211 Herrsching am Ammersee, Germany, Telephone: (49)8152-275-0, Fax: (49)8152-2658, E-mail: info@hamamatsu.de
France: Hamamatsu Photonics France S.A.R.L.: 19, Rue du Saule Trapu, Parc du Moulin de Massy, 91882 Massy, 2002 (49)8152-375-0, Fax: (31) 69 53 71 10, Fax: 33(1) 69 53 71 10, E-mail: info@hamamatsu.dr
United Kingdom: Hamamatsu Photonics UK Limited: 2 Howard Court, 10 Tewin Road, Welwyn Garden City, Heritodshire AL7 1BW, United Kingdom, Telephone: (44)1707-2294888, Fax: (44)1707-325777, E-mail: info@hamamatsu.co.uk
North Europe: Hamamatsu Photonics Norden AB: Torshamnsgatan 35 SE-164 40 Kista, Sweden, Telephone: (46)8-509-031-01, E-mail: info@hamamatsu.se
Hally: Hamamatsu Photonics Istala S.L.I: Strada della Moia, 1 int. 6, 20020 Arses, (Milano), Italy, Telephone: (39)02-93851733, Fax: (39)02-93851741, E-mail: info@hamamatsu.it
China: Hamamatsu Photonics (China) Co., Ltd.: B1201 Jiaming Center, No.27 Dongsanhuan Beilu, Chaoyang District, Beijing 100020, China, Telephone: (86)10-6586-6006, Fax: (86)10-6586-2866, E-mail: hpc@hamamatsu.com.cn